

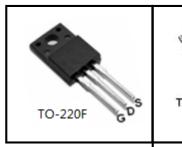
## **600V N-Channel MOSFET**

#### **FEATURES**

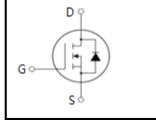
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)







Device Marking and Package Information			
Device	Package	Marking	
CS20N60F	TO-220F	CS20N60F	
CS20N60P	TO-220	CS20N60P	

<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted					
Parameter	Sumb al	Value		l last	
raiametei	Symbol	TO-220F	TO-220	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	600		V	
Continuous Drain Current	I <sub>D</sub>	20		А	
Pulsed Drain Current (note1)	I <sub>DM</sub>	80		А	
Gate-Source Voltage	$V_{GSS}$	±	30	V	
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	566		mJ	
Avalanche Current (note1)	I <sub>AS</sub>	11		А	
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	339		mJ	
Power Dissipation (T <sub>C</sub> = 25°C)	$P_{D}$	120	140	W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~	+150	۰C	

Thermal Resistance				
	Ob-al	Va		
Parameter	Symbol	TO-220F	TO-220	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	1.9	1.2	00.004
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5	60	- °C/W



<b>Specifications</b> $T_J = 25^{\circ}C$ , unless otherwise noted								
Parameter	Symbol	Took Conditions	Value			Unit		
		Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	600			٧		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 600V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA		
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 30V$			±100	nA		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V		
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_{D} = 10A$		0.32	0.40	Ω		
Dynamic								
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$ f = 1.0MHz		2521		pF		
Output Capacitance	C <sub>oss</sub>			264				
Reverse Transfer Capacitance	C <sub>rss</sub>			35				
Total Gate Charge	$Q_g$	$V_{DD} = 480V, I_{D} = 20A,$ $V_{GS} = 10V$		76		nC		
Gate-Source Charge	$Q_{gs}$			13				
Gate-Drain Charge	$Q_{gd}$	- GS		32				
Turn-on Delay Time	t <sub>d(on)</sub>			53		ns		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 300V, I_{D} = 20A,$		44				
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		321				
Turn-off Fall Time	t <sub>f</sub>			80				
Drain-Source Body Diode Character	istics							
Continuous Body Diode Current	I <sub>s</sub>				20	A		
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			80			
Body Diode Voltage	$V_{SD}$	$T_J = 25^{\circ}C$ , $I_{SD} = 10A$ , $V_{GS} = 0V$			1.4	V		
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 20A,$ $di_{F}/dt = 100A / \mu s$		733		ns		
Reverse Recovery Charge	Q <sub>rr</sub>			6.5		μC		

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=10mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%



### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics ( $T_J = 25^{\circ}C$ )

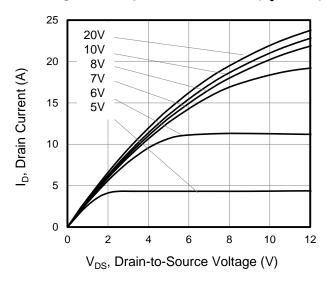


Figure 3. Drain Current vs. Temperature

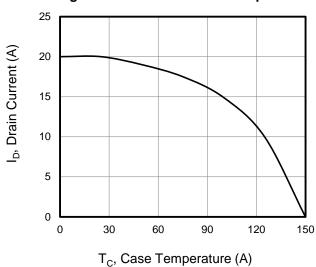


Figure 5. Transfer Characteristics

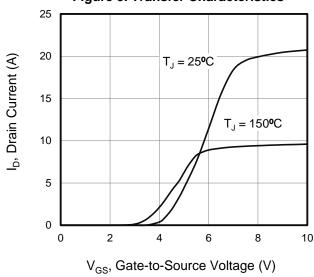


Figure 2. Body Diode Forward Voltage

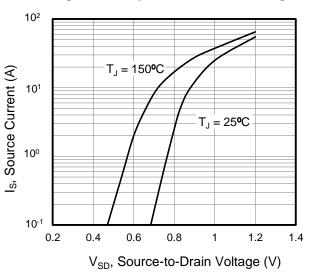


Figure 4. BV<sub>DSS</sub> Variation vs. Temperature

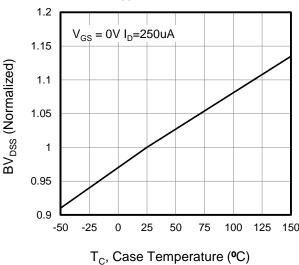
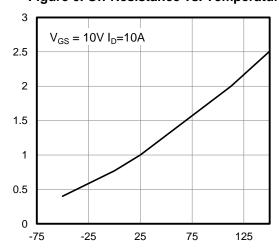


Figure 6. On-Resistance vs. Temperature



T<sub>J</sub>, Junction Temperature (°C)

R<sub>DS(on)</sub>, On-Resistance (Normalized)



### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

V<sub>GS</sub>, Gate-to-Source Voltage (V)

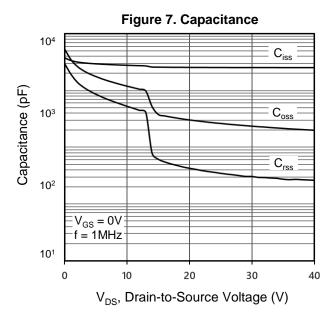


Figure 9. Transient Thermal Impedance
TO-220

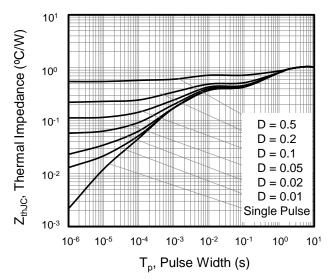


Figure 8. Gate Charge

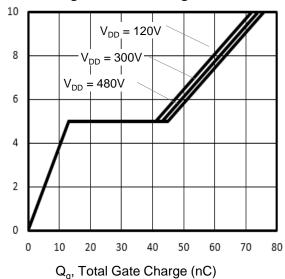


Figure 9. Transient Thermal Impedance

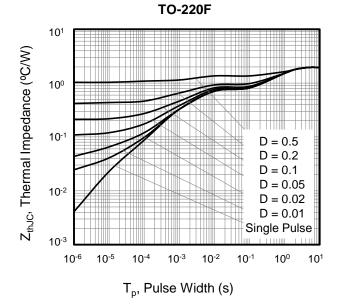




Figure A: Gate Charge Test Circuit and Waveform

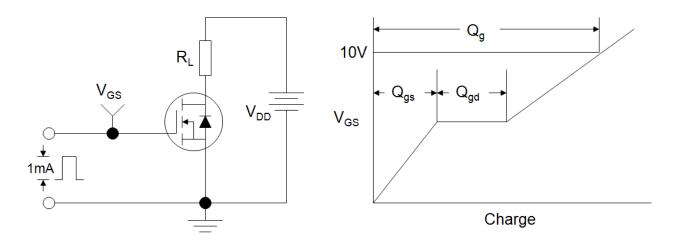


Figure B: Resistive Switching Test Circuit and Waveform

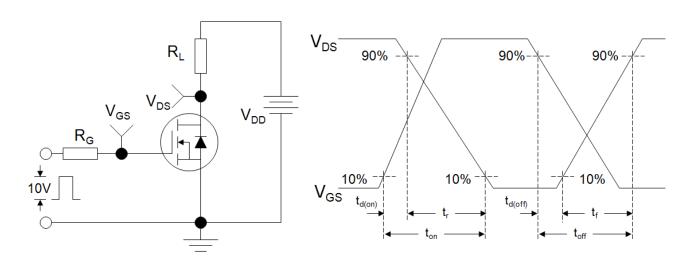
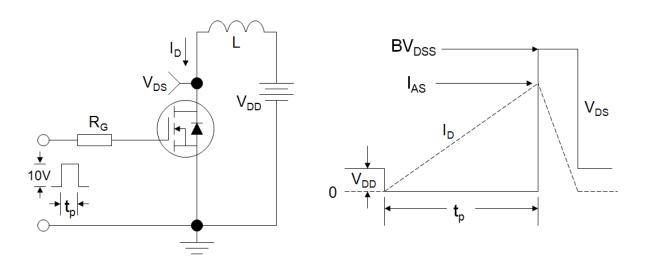
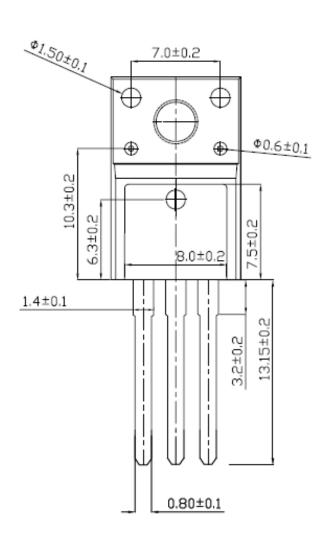


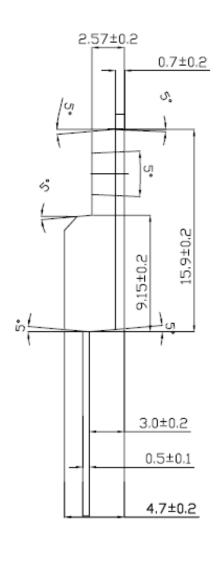
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





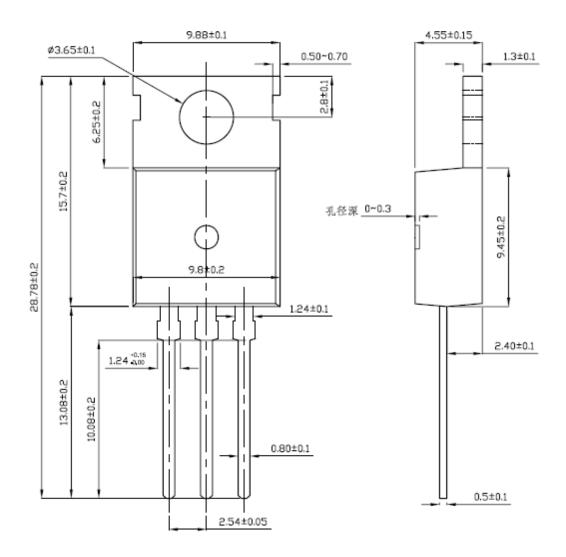
## **TO-220F**







# **TO-220**





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